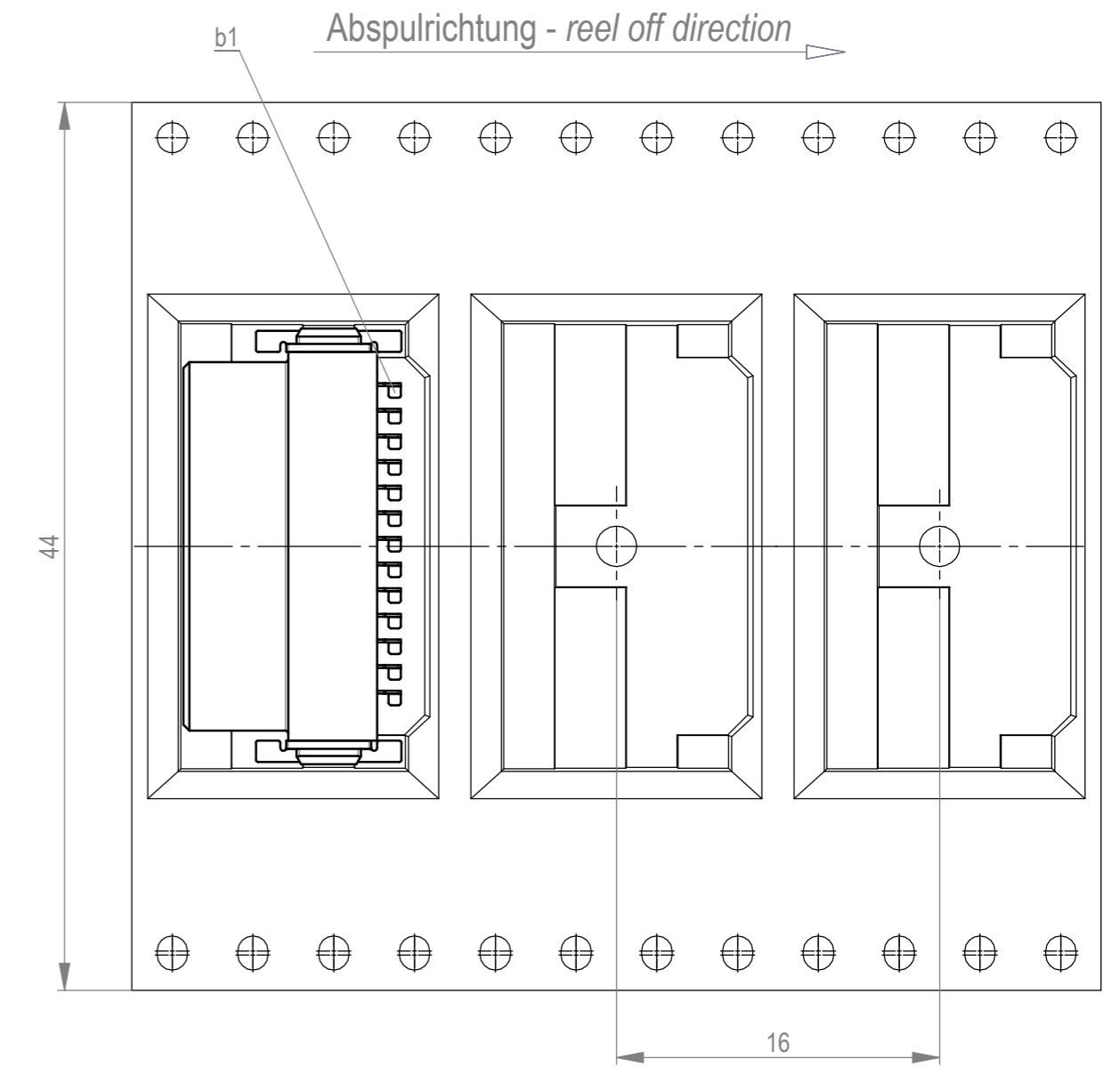
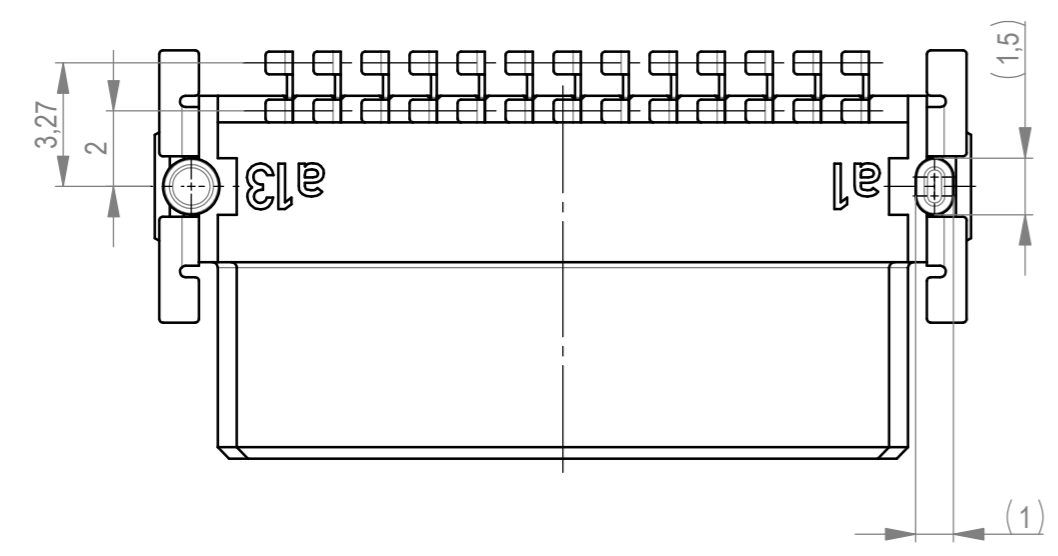
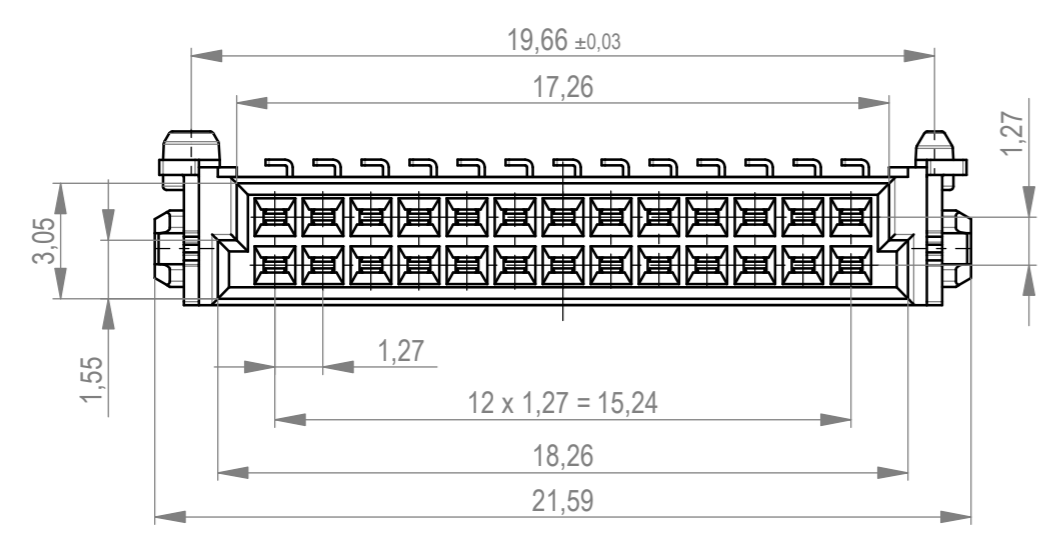
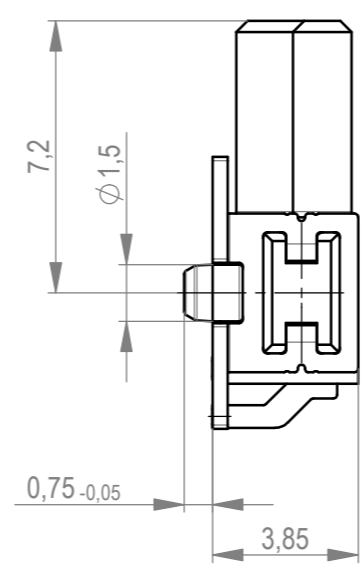
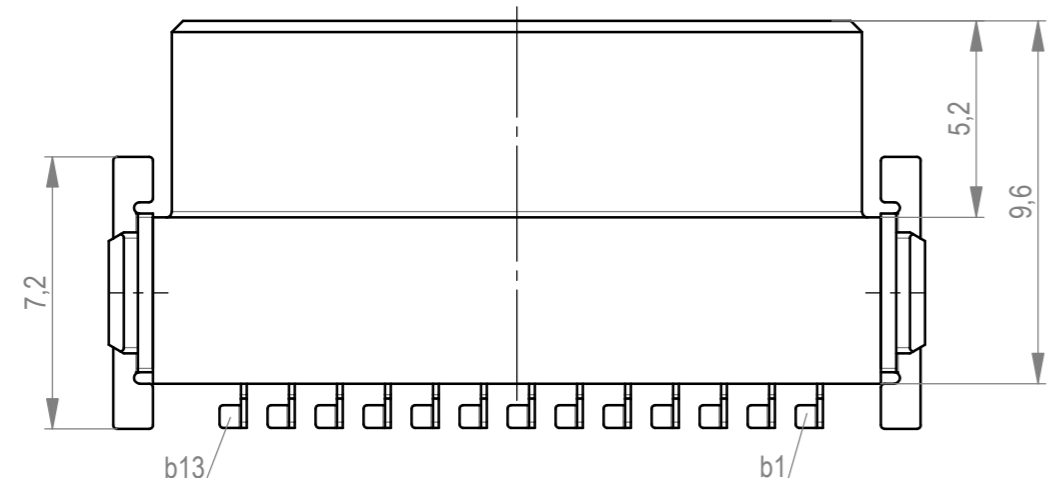
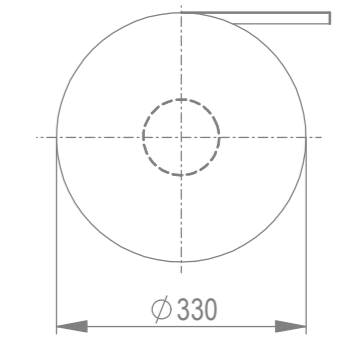
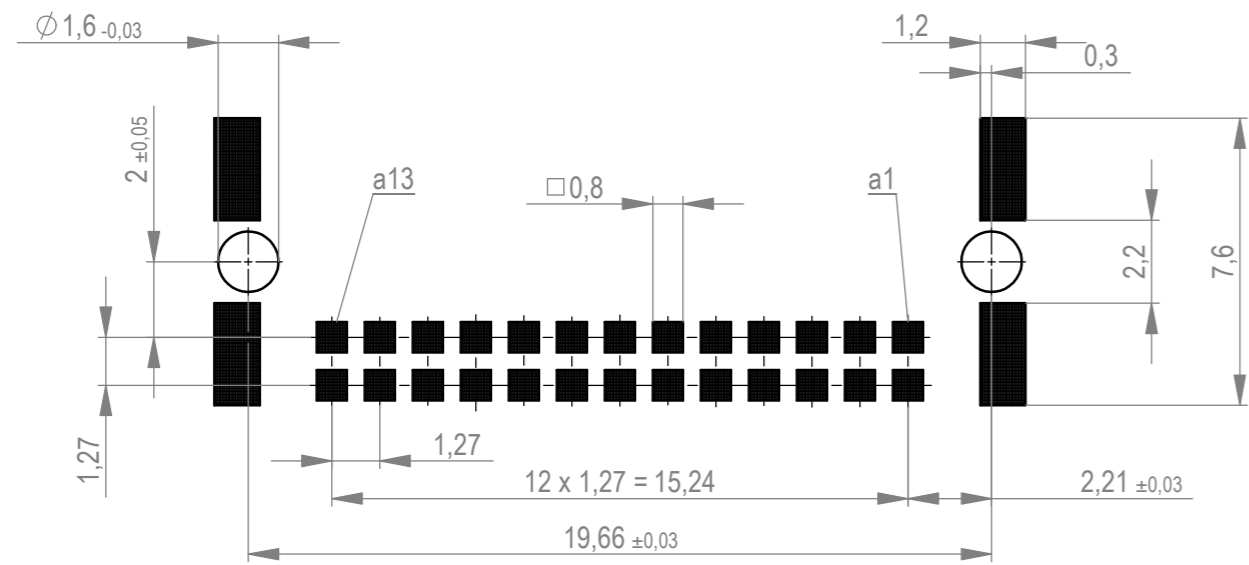


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs



Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

BA7-03 - Standard Bauhöhe
type7-03 - standard assembly height

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Dimension no.	Tolerances		Scale	5:1
	ISO 8015	All Dimensions in mm	Material	
Customer drawing:	Subject to modification without prior notice. Drawing will not be updated.		Federl. SMC-Q 26-SMD-BA7-03 Female SMC-Q 26-SMD-type7-03	
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g	25.05.2021			I
Index	Date		Class	A2